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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Ohtani                      Art Unit : 1765  
Serial No.: 09/596,755                      Examiner : Robert Kunemund  
Filed : June 15, 2000  
Title : MANUFACTURING METHOD OF SEMICONDUCTOR AND  
MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

Commissioner for Patents  
Washington, D.C. 20231

TRANSMITTAL LETTER AND PETITION FOR AUTOMATIC EXTENSION

Correspondence relating to this application is enclosed.  
The required fees are computed below. Please apply any charges  
not covered, or any credits, to Deposit Account No. 06-1050.

Total Claims	44	-	20	=	24	\$432
Independent	7	-	3	=	4	<u>\$320</u>
TOTAL FEE DUE						\$752

A check for \$752 is attached.

Respectfully submitted,

Date: 1/24/01

*[Signature]* REC NO. 40,631  
For Scott C. Harris  
Reg. No. 32,030

Fish & Richardson P.C.  
PTO Customer No. 20985  
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CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being  
deposited with the United States Postal Service as first class mail with  
sufficient postage on the date indicated below and is addressed to the  
Commissioner for Patents, Washington, D.C. 20231.

Signature

Susan Regan

Print Name of Person Signing Certificate

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AMENDMENT

Sir:

In response to the Official Action dated October 24, 2000,  
Paper No. 2, in the above-referenced application, please amend  
the above-identified application as follows.

In the Claims:

Please cancel claim 1 without prejudice.

Please add the following new claims.

2. (New) A method for manufacturing a semiconductor device  
comprising steps of:

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Susan Regan